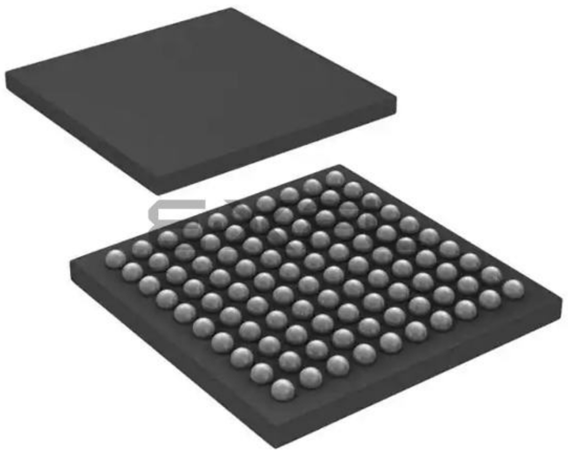


Details	
Product Status	Active
Core Processor	AVR
Core Size	32-Bit Single-Core
Speed	66MHz
Connectivity	EBI/EMI, I²C, IrDA, Memory Card, SPI, SSC, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, POR, WDT
Number of I/O	88
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128K x 8
Voltage - Supply (Vcc/Vdd)	1.75V ~ 3.6V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-VFBGA
Supplier Device Package	100-VFBGA (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/at32uc3a4256-c1ut

Figure 3-2. LQFP144 Pinout

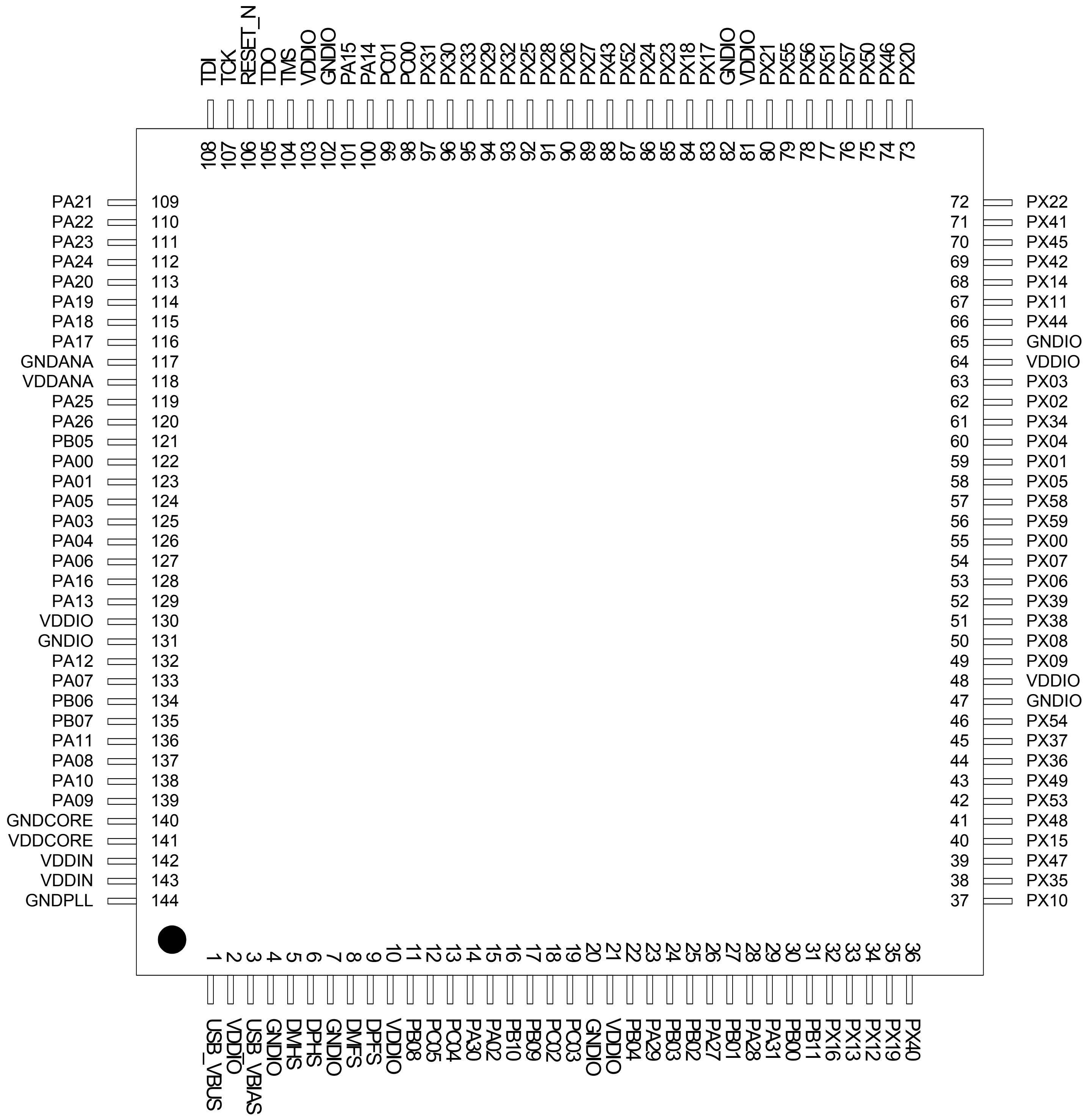
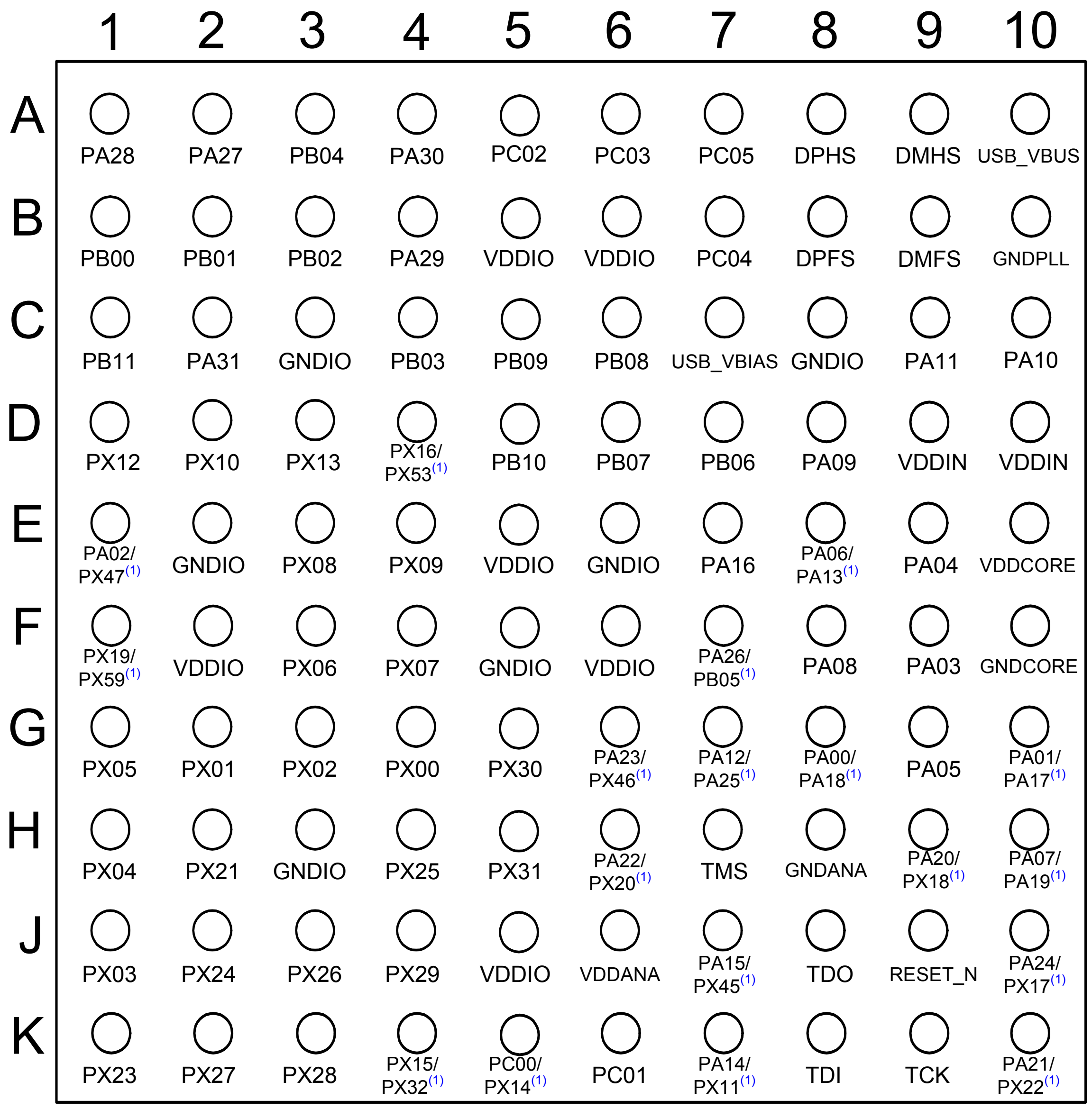


Figure 3-3. VFBGA100 Pinout (top view)



	1	2	3	4	5	6	7	8	9	10
A	PA28	PA27	PB04	PA30	PC02	PC03	PC05	DPHS	DMHS	USB_VBUS
B	PB00	PB01	PB02	PA29	VDDIO	VDDIO	PC04	DPFS	DMFS	GNDPLL
C	PB11	PA31	GNDIO	PB03	PB09	PB08	USB_VBIAS	GNDIO	PA11	PA10
D	PX12	PX10	PX13	PX16/ PX53[1]	PB10	PB07	PB06	PA09	VDDIN	VDDIN
E	PA02/ PX47[1]	GNDIO	PX08	PX09	VDDIO	GNDIO	PA16	PA06/ PA13[1]	PA04	VDDCORE
F	PX19/ PX59[1]	VDDIO	PX06	PX07	GNDIO	VDDIO	PA26/ PB05[1]	PA08	PA03	GNDCORE
G	PX05	PX01	PX02	PX00	PX30	PA23/ PX46[1]	PA12/ PA25[1]	PA00/ PA18[1]	PA05	PA01/ PA17[1]
H	PX04	PX21	GNDIO	PX25	PX31	PA22/ PX20[1]	TMS	GNDANA	PA20/ PX18[1]	PA07/ PA19[1]
J	PX03	PX24	PX26	PX29	VDDIO	VDDANA	PA15/ PX45[1]	TDO	RESET_N	PA24/ PX17[1]
K	PX23	PX27	PX28	PX15/ PX32[1]	PC00/ PX14[1]	PC01	PA14/ PX11[1]	TDI	TCK	PA21/ PX22[1]

Note: 1. Those balls are physically connected to 2 GPIOs. Software must managed carrefully the GPIO configuration to avoid electrical conflict

Table 3-6. Signal Description List

Signal Name	Function	Type	Active Level	Comments
RESET_N	Reset Pin	Input	Low	
DMA Controller - DMACA (optional)				
DMAACK[1:0]	DMA Acknowledge	Output		
DMARQ[1:0]	DMA Requests	Input		
External Interrupt Controller - EIC				
EXTINT[7:0]	External Interrupt Pins	Input		
SCAN[7:0]	Keypad Scan Pins	Output		
NMI	Non-Maskable Interrupt Pin	Input	Low	
General Purpose Input/Output pin - GPIOA, GPIOB, GPIOC, GPIOX				
PA[31:0]	Parallel I/O Controller GPIO port A	I/O		
PB[11:0]	Parallel I/O Controller GPIO port B	I/O		
PC[5:0]	Parallel I/O Controller GPIO port C	I/O		
PX[59:0]	Parallel I/O Controller GPIO port X	I/O		
External Bus Interface - EBI				
ADDR[23:0]	Address Bus	Output		
CAS	Column Signal	Output	Low	
CFCE1	Compact Flash 1 Chip Enable	Output	Low	
CFCE2	Compact Flash 2 Chip Enable	Output	Low	
CFRNW	Compact Flash Read Not Write	Output		
DATA[15:0]	Data Bus	I/O		
NANDOE	NAND Flash Output Enable	Output	Low	
NANDWE	NAND Flash Write Enable	Output	Low	
NCS[5:0]	Chip Select	Output	Low	
NRD	Read Signal	Output	Low	
NWAIT	External Wait Signal	Input	Low	
NWE0	Write Enable 0	Output	Low	
NWE1	Write Enable 1	Output	Low	
RAS	Row Signal	Output	Low	

The register file is organized as sixteen 32-bit registers and includes the Program Counter, the Link Register, and the Stack Pointer. In addition, register R12 is designed to hold return values from function calls and is used implicitly by some instructions.

4.3 The AVR32UC CPU

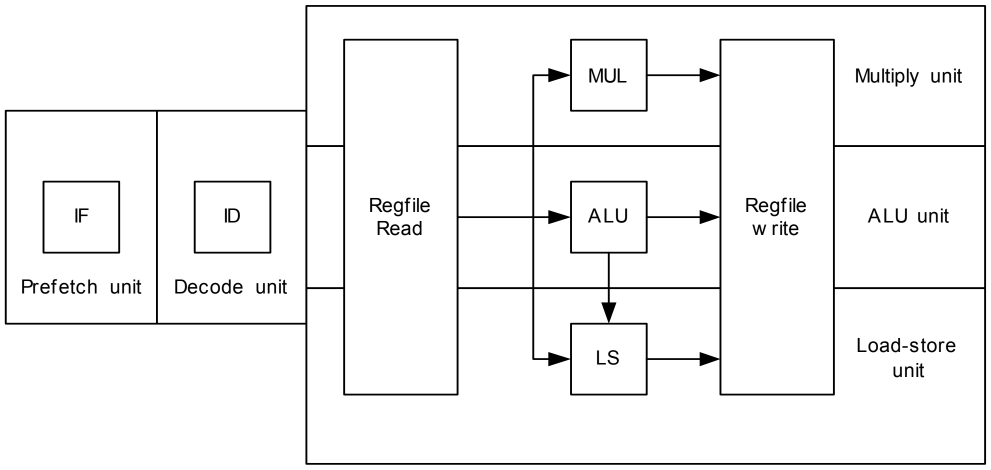
The AVR32UC CPU targets low- and medium-performance applications, and provides an advanced OCD system, no caches, and a Memory Protection Unit (MPU). Java acceleration hardware is not implemented.

AVR32UC provides three memory interfaces, one High Speed Bus master for instruction fetch, one High Speed Bus master for data access, and one High Speed Bus slave interface allowing other bus masters to access data RAMs internal to the CPU. Keeping data RAMs internal to the CPU allows fast access to the RAMs, reduces latency, and guarantees deterministic timing. Also, power consumption is reduced by not needing a full High Speed Bus access for memory accesses. A dedicated data RAM interface is provided for communicating with the internal data RAMs.

A local bus interface is provided for connecting the CPU to device-specific high-speed systems, such as floating-point units and fast GPIO ports. This local bus has to be enabled by writing the LOCEN bit in the CPUCR system register. The local bus is able to transfer data between the CPU and the local bus slave in a single clock cycle. The local bus has a dedicated memory range allocated to it, and data transfers are performed using regular load and store instructions. Details on which devices that are mapped into the local bus space is given in the Memories chapter of this data sheet.

Figure 4-1 on page 23 displays the contents of AVR32UC.

Figure 4-2. The AVR32UC Pipeline



4.3.2 AVR32A Microarchitecture Compliance

AVR32UC implements an AVR32A microarchitecture. The AVR32A microarchitecture is targeted at cost-sensitive, lower-end applications like smaller microcontrollers. This microarchitecture does not provide dedicated hardware registers for shadowing of register file registers in interrupt contexts. Additionally, it does not provide hardware registers for the return address registers and return status registers. Instead, all this information is stored on the system stack. This saves chip area at the expense of slower interrupt handling.

Upon interrupt initiation, registers R8-R12 are automatically pushed to the system stack. These registers are pushed regardless of the priority level of the pending interrupt. The return address and status register are also automatically pushed to stack. The interrupt handler can therefore use R8-R12 freely. Upon interrupt completion, the old R8-R12 registers and status register are restored, and execution continues at the return address stored popped from stack.

The stack is also used to store the status register and return address for exceptions and *scall*. Executing the *rete* or *rets* instruction at the completion of an exception or system call will pop this status register and continue execution at the popped return address.

4.3.3 Java Support

AVR32UC does not provide Java hardware acceleration.

4.3.4 Memory Protection

The MPU allows the user to check all memory accesses for privilege violations. If an access is attempted to an illegal memory address, the access is aborted and an exception is taken. The MPU in AVR32UC is specified in the AVR32UC Technical Reference manual.

4.3.5 Unaligned Reference Handling

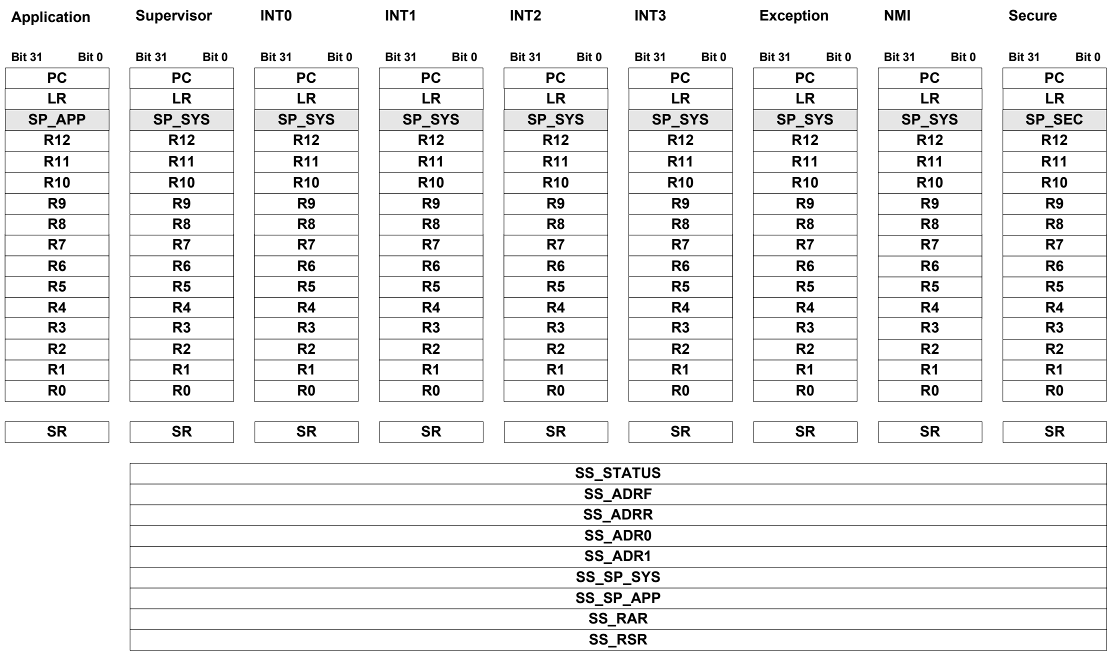
AVR32UC does not support unaligned accesses, except for doubleword accesses. AVR32UC is able to perform word-aligned *st.d* and *ld.d*. Any other unaligned memory access will cause an address exception. Doubleword-sized accesses with word-aligned pointers will automatically be performed as two word-sized accesses.

4.4 Programming Model

4.4.1 Register File Configuration

The AVR32UC register file is shown below.

Figure 4-3. The AVR32UC Register File



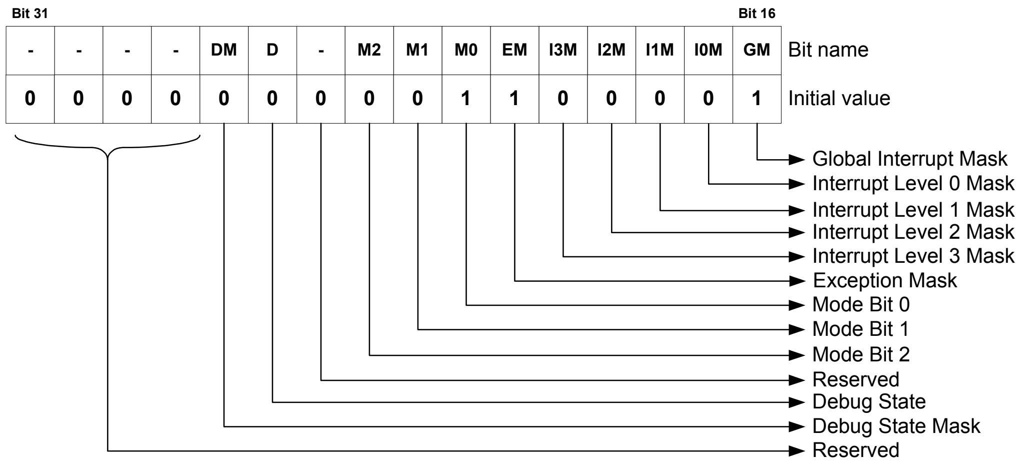
Application	Supervisor	INT0	INT1	INT2	INT3	Exception	NMI	Secure
Bit 31 Bit 0	Bit 31 Bit 0	Bit 31 Bit 0	Bit 31 Bit 0	Bit 31 Bit 0	Bit 31 Bit 0	Bit 31 Bit 0	Bit 31 Bit 0	Bit 31 Bit 0
PC	PC	PC	PC	PC	PC	PC	PC	PC
LR	LR	LR	LR	LR	LR	LR	LR	LR
SP_APP	SP_SYS	SP_SYS	SP_SYS	SP_SYS	SP_SYS	SP_SYS	SP_SYS	SP_SEC
R12	R12	R12	R12	R12	R12	R12	R12	R12
R11	R11	R11	R11	R11	R11	R11	R11	R11
R10	R10	R10	R10	R10	R10	R10	R10	R10
R9	R9	R9	R9	R9	R9	R9	R9	R9
R8	R8	R8	R8	R8	R8	R8	R8	R8
R7	R7	R7	R7	R7	R7	R7	R7	R7
R6	R6	R6	R6	R6	R6	R6	R6	R6
R5	R5	R5	R5	R5	R5	R5	R5	R5
R4	R4	R4	R4	R4	R4	R4	R4	R4
R3	R3	R3	R3	R3	R3	R3	R3	R3
R2	R2	R2	R2	R2	R2	R2	R2	R2
R1	R1	R1	R1	R1	R1	R1	R1	R1
R0	R0	R0	R0	R0	R0	R0	R0	R0
SR	SR	SR	SR	SR	SR	SR	SR	SR

SS_STATUS
SS_ADRF
SS_ADRR
SS_ADR0
SS_ADR1
SS_SP_SYS
SS_SP_APP
SS_RAR
SS_RSR

4.4.2 Status Register Configuration

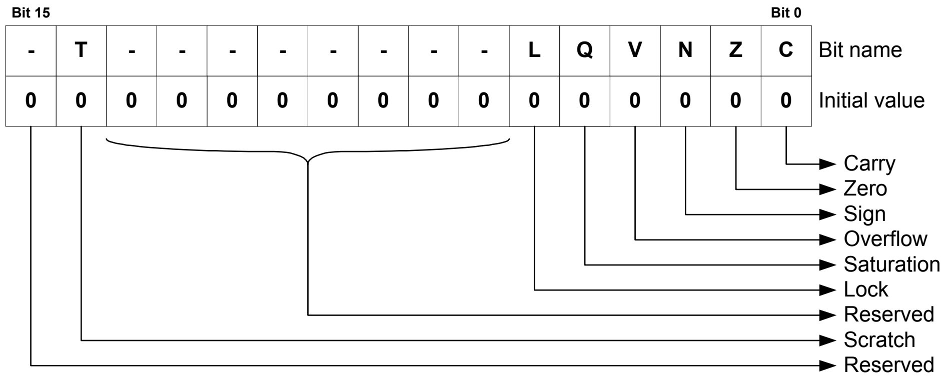
The Status Register (SR) is split into two halfwords, one upper and one lower, see Figure 4-4 on page 26 and Figure 4-5 on page 27. The lower word contains the C, Z, N, V, and Q condition code flags and the R, T, and L bits, while the upper halfword contains information about the mode and state the processor executes in. Refer to the *AVR32 Architecture Manual* for details.

Figure 4-4. The Status Register High Halfword



Bit 31															Bit 16	
-	-	-	-	DM	D	-	M2	M1	M0	EM	I3M	I2M	I1M	I0M	GM	Bit name
0	0	0	0	0	0	0	0	0	1	1	0	0	0	0	1	Initial value

Figure 4-5. The Status Register Low Halfword



4.4.3 Processor States

4.4.3.1 Normal RISC State

The AVR32 processor supports several different execution contexts as shown in Table 4-2 on page 27.

Table 4-2. Overview of Execution Modes, their Priorities and Privilege Levels.

Priority	Mode	Security	Description
1	Non Maskable Interrupt	Privileged	Non Maskable high priority interrupt mode
2	Exception	Privileged	Execute exceptions
3	Interrupt 3	Privileged	General purpose interrupt mode
4	Interrupt 2	Privileged	General purpose interrupt mode
5	Interrupt 1	Privileged	General purpose interrupt mode
6	Interrupt 0	Privileged	General purpose interrupt mode
N/A	Supervisor	Privileged	Runs supervisor calls
N/A	Application	Unprivileged	Normal program execution mode

Mode changes can be made under software control, or can be caused by external interrupts or exception processing. A mode can be interrupted by a higher priority mode, but never by one with lower priority. Nested exceptions can be supported with a minimal software overhead.

When running an operating system on the AVR32, user processes will typically execute in the application mode. The programs executed in this mode are restricted from executing certain instructions. Furthermore, most system registers together with the upper halfword of the status register cannot be accessed. Protected memory areas are also not available. All other operating modes are privileged and are collectively called System Modes. They have full access to all privileged and unprivileged resources. After a reset, the processor will be in supervisor mode.

4.4.3.2 Debug State

The AVR32 can be set in a debug state, which allows implementation of software monitor routines that can read out and alter system information for use during application development. This implies that all system and application registers, including the status registers and program counters, are accessible in debug state. The privileged instructions are also available.

Table 4-3. System Registers (Continued)

Reg #	Address	Name	Function
26	104	JAVA_LV3	Unused in AVR32UC
27	108	JAVA_LV4	Unused in AVR32UC
28	112	JAVA_LV5	Unused in AVR32UC
29	116	JAVA_LV6	Unused in AVR32UC
30	120	JAVA_LV7	Unused in AVR32UC
31	124	JTBA	Unused in AVR32UC
32	128	JBCR	Unused in AVR32UC
33-63	132-252	Reserved	Reserved for future use
64	256	CONFIG0	Configuration register 0
65	260	CONFIG1	Configuration register 1
66	264	COUNT	Cycle Counter register
67	268	COMPARE	Compare register
68	272	TLBEHI	Unused in AVR32UC
69	276	TLBELO	Unused in AVR32UC
70	280	PTBR	Unused in AVR32UC
71	284	TLBEAR	Unused in AVR32UC
72	288	MMUCR	Unused in AVR32UC
73	292	TLBARLO	Unused in AVR32UC
74	296	TLBARHI	Unused in AVR32UC
75	300	PCCNT	Unused in AVR32UC
76	304	PCNT0	Unused in AVR32UC
77	308	PCNT1	Unused in AVR32UC
78	312	PCCR	Unused in AVR32UC
79	316	BEAR	Bus Error Address Register
80	320	MPUAR0	MPU Address Register region 0
81	324	MPUAR1	MPU Address Register region 1
82	328	MPUAR2	MPU Address Register region 2
83	332	MPUAR3	MPU Address Register region 3
84	336	MPUAR4	MPU Address Register region 4
85	340	MPUAR5	MPU Address Register region 5
86	344	MPUAR6	MPU Address Register region 6
87	348	MPUAR7	MPU Address Register region 7
88	352	MPUPSR0	MPU Privilege Select Register region 0
89	356	MPUPSR1	MPU Privilege Select Register region 1
90	360	MPUPSR2	MPU Privilege Select Register region 2
91	364	MPUPSR3	MPU Privilege Select Register region 3

7. Electrical Characteristics

7.1 Absolute Maximum Ratings*

Operating Temperature	-40°C to +85°C
Storage Temperature	-60°C to +150°C
Voltage on Input Pin with respect to Ground	-0.3V to 3.6V
Maximum Operating Voltage (VDDCORE)	1.95V
Maximum Operating Voltage (VDDIO)	3.6V
Total DC Output Current on all I/O Pin for TQFP144 package	370 mA
for TFBGA144 package	370 mA

*NOTICE: Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Table 7-9. BOD Timing

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
T_{BOD}	Minimum time with VDDCORE < VBOD to detect power failure	Falling VDDCORE from 1.8V to 1.1V		300	800	ns

7.5.3 Reset Sequence

Table 7-10. Electrical Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
V_{DDRR}	VDDIN/VDDIO rise rate to ensure power-on-reset		0.8			V/ms
V_{POR+}	Rising threshold voltage: voltage up to which device is kept under reset by POR on rising VDDIN	Rising VDDIN: $V_{RESTART}$ -> V_{POR+}		2.7		V
V_{POR-}	Falling threshold voltage: voltage when POR resets device on falling VDDIN	Falling VDDIN: 3.3V -> V_{POR-}		2.7		V
$V_{RESTART}$	On falling VDDIN, voltage must go down to this value before supply can rise again to ensure reset signal is released at V_{POR+}	Falling VDDIN: 3.3V -> $V_{RESTART}$			0.2	V
T_{SSU1}	Time for Cold System Startup: Time for CPU to fetch its first instruction (RCosc not calibrated)		480		960	µs
T_{SSU2}	Time for Hot System Startup: Time for CPU to fetch its first instruction (RCosc calibrated)			420		µs

Figure 7-3. MCU Cold Start-Up

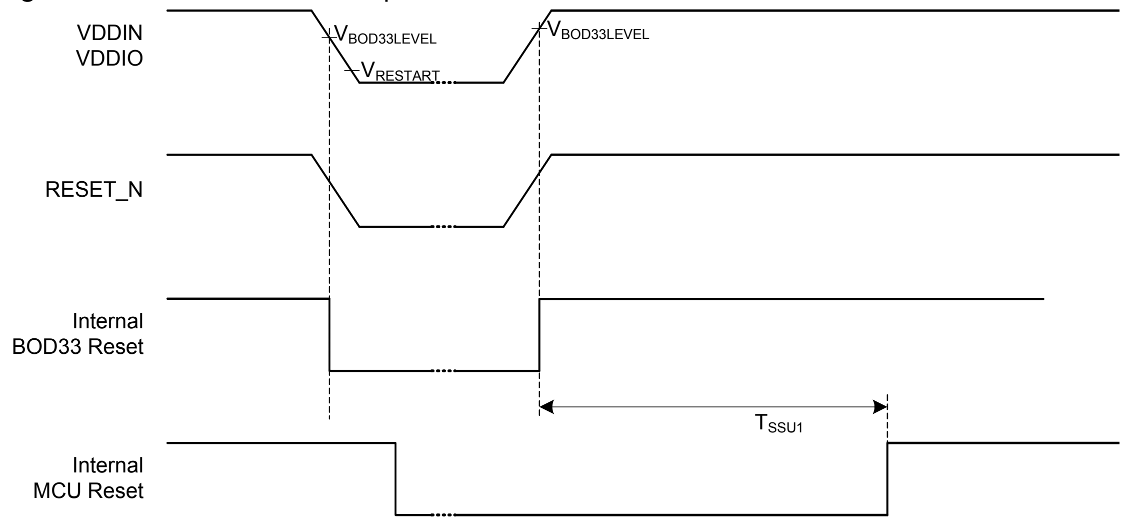


Figure 7-4. MCU Cold Start-Up RESET_N Externally Driven

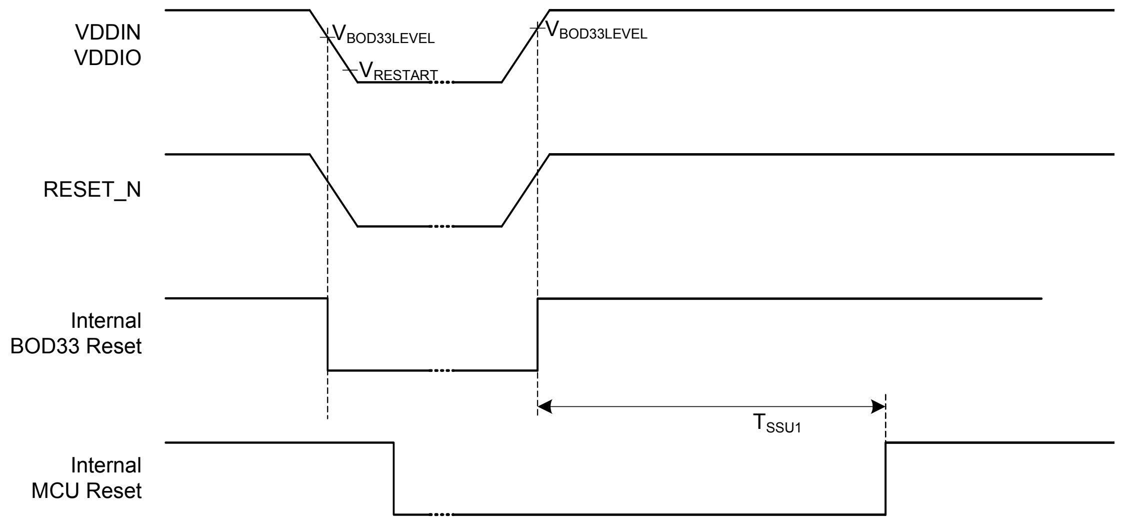
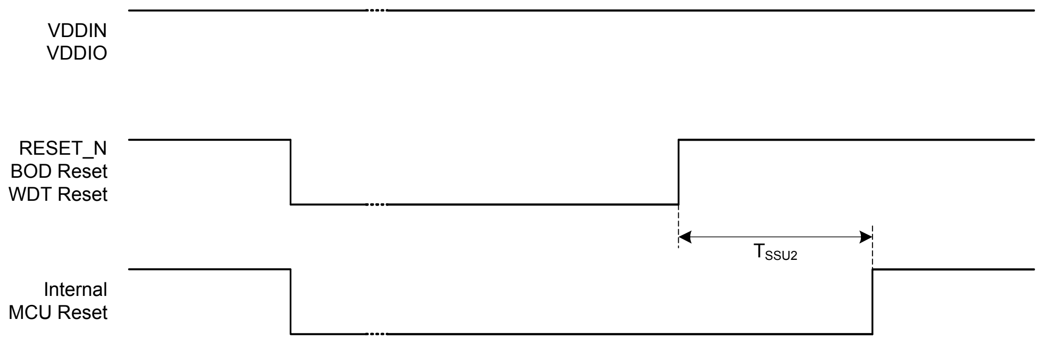


Figure 7-5. MCU Hot Start-Up



7.6.1 Power Consumtion for Different Sleep Modes

Table 7-12. Power Consumption for Different Sleep Modes

Mode	Conditions[1]		Typ.	Unit
Active	- CPU running a recursive Fibonacci Algorithm from flash and clocked from PLL0 at f MHz. - Flash High Speed mode disable (f < 66 MHz) - Voltage regulator is on. - XIN0: external clock. Xin1 Stopped. XIN32 stopped. - All peripheral clocks activated with a division by 8. - GPIOs are inactive with internal pull-up, JTAG unconnected with external pullup and Input pins are connected to GND		0.626xf(MHz)+2.257	mA/MHz
	Same conditions with Flash High Speed mode enable (66< f < 84 MHz)		0.670xf(MHz)+2.257	mA/MHz
	Same conditions with Flash High Speed mode disable at 60 MHz		40	mA
Idle	See Active mode conditions		0.349xf(MHz)+0.968	mA/MHz
	Same conditions at 60 MHz		21.8	mA
Frozen	See Active mode conditions		0.098xf(MHz)+1.012	mA/MHz
	Same conditions at 60 MHz		6.6	mA
Standby	See Active mode conditions		0.066xf(MHz)+1.010	mA/MHz
	Same conditions at 60 MHz		4.6	mA
Stop	- CPU running in sleep mode - XIN0, Xin1 and XIN32 are stopped. - All peripheral clocks are desactived. - GPIOs are inactive with internal pull-up, JTAG unconnected with external pullup and Input pins are connected to GND.		96	µA
Deepstop	See Stop mode conditions		54	µA
Static	T_A = 25 °C CPU is in static mode GPIOs on internal pull-up All peripheral clocks de-activated DM and DP pins connected to ground XIN0, Xin1 and XIN32 are stopped	on Amp0	31	µA

Notes: 1. Core frequency is generated from XIN0 using the PLL.

7.8 Oscillator Characteristics

The following characteristics are applicable to the operating temperature range: T_A = -40°C to 85°C and worst case of power supply, unless otherwise specified.

7.8.1 Slow Clock RC Oscillator

Table 7-17. RC Oscillator Frequency

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
F_{RC}	RC Oscillator Frequency	Calibration point: T_A = 85°C		115.2	116	KHz
		T_A = 25°C		112		KHz
		T_A = -40°C	105	108		KHz

7.8.2 32 KHz Oscillator

Table 7-18. 32 KHz Oscillator Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$1/(t_{CP32KHz})$	Oscillator Frequency	External clock on XIN32			30	MHz
		Crystal		32 768		Hz
C_L	Equivalent Load Capacitance		6		12.5	pF
ESR	Crystal Equivalent Series Resistance				100	KΩ
t_{ST}	Startup Time	C_L = 6pF(1) C_L = 12.5pF(1)			600 1200	ms
t_{CH}	XIN32 Clock High Half-period		0.4 t_{CP}		0.6 t_{CP}	
t_{CL}	XIN32 Clock Low Half-period		0.4 t_{CP}		0.6 t_{CP}	
C_{IN}	XIN32 Input Capacitance				5	pF
I_{OSC}	Current Consumption	Active mode			1.8	µA
		Standby mode			0.1	µA

Note: 1. C_L is the equivalent load capacitance.

Table 7-26. Transfer Characteristics in 10-bit mode

Parameter	Conditions	Min.	Typ.	Max.	Unit
Resolution			10		Bit
Absolute Accuracy	ADC Clock = 5 MHz			3	LSB
Integral Non-linearity	ADC Clock = 5 MHz		1.5	2	LSB
Differential Non-linearity	ADC Clock = 5 MHz		1	2	LSB
	ADC Clock = 2.5 MHz		0.6	1	LSB
Offset Error	ADC Clock = 5 MHz	-2		2	LSB
Gain Error	ADC Clock = 5 MHz	-2		2	LSB

7.10 USB Transceiver Characteristics

7.10.1 Electrical Characteristics

Table 7-27. Electrical Parameters

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
R_{EXT}	Recommended External USB Series Resistor	In series with each USB pin with ±5%		39		Ω
R_{BIAS}	VBIAS External Resistor [(1)]	±1%		6810		Ω
C_{BIAS}	VBIAS External Capcitor			10		pF

1. The USB on-chip buffers comply with the Universal Serial Bus (USB) v2.0 standard. All AC parameters related to these buffers can be found within the USB 2.0 electrical specifications.

7.10.2 Static Power Consumption

Table 7-28. Static Power Consumption

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_{BIAS}	Bias current consumption on VBG				1	µA
$I_{VDDUTMI}$	HS Transceiver and I/O current consumption				8	µA
	FS/HS Transceiver and I/O current consumption	If cable is connected, add 200µA (typical) due to Pull-up/Pull-down current consumption			3	µA

7.10.3 Dynamic Power Consumption

Table 7-29. Dynamic Power Consumption

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_{BIAS}	Bias current consumption on VBG			0.7	0.8	mA

7.11 EBI Timings

7.11.1 SMC Signals

These timings are given for worst case process, T = 85·C, VDDIO = 3V and 40 pF load capacitance.

Table 7-30. SMC Clock Signal

Symbol	Parameter	Max.[1]	Unit
$1/(t_{CPSMC})$	SMC Controller Clock Frequency	$1/(t_{cpcpu})$	MHz

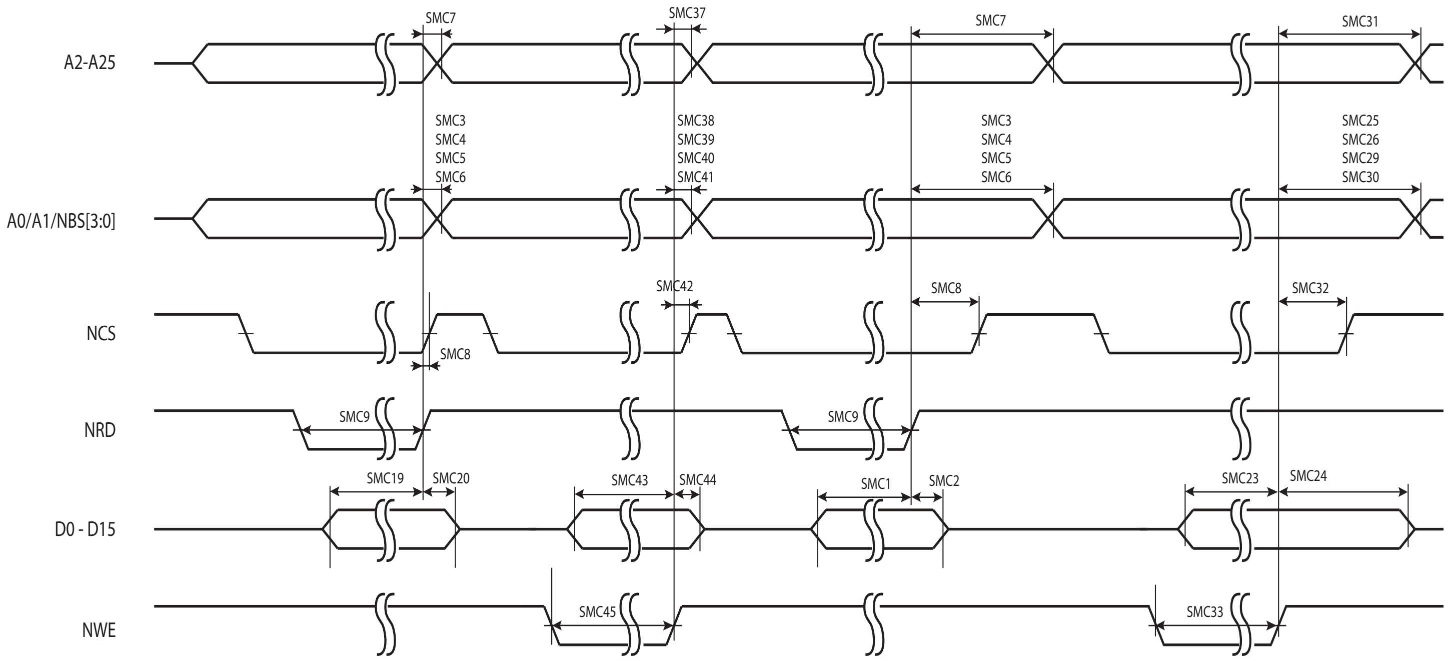
Note: 1. The maximum frequency of the SMC interface is the same as the max frequency for the HSB.

Table 7-31. SMC Read Signals with Hold Settings

Symbol	Parameter	Min.	Unit
NRD Controlled (READ_MODE = 1)			
SMC_1	Data Setup before NRD High	12	ns
SMC_2	Data Hold after NRD High	0	ns
SMC_3	NRD High to NBS0/A0 Change[1]	nrd hold length * t_{CPSMC} - 1.3	ns
SMC_4	NRD High to NBS1 Change[1]	nrd hold length * t_{CPSMC} - 1.3	ns
SMC_5	NRD High to NBS2/A1 Change[1]	nrd hold length * t_{CPSMC} - 1.3	ns
SMC_7	NRD High to A2 - A23 Change[1]	nrd hold length * t_{CPSMC} - 1.3	ns
SMC_8	NRD High to NCS Inactive[1]	(nrd hold length - ncs rd hold length) * t_{CPSMC} - 2.3	ns
SMC_9	NRD Pulse Width	nrd pulse length * t_{CPSMC} - 1.4	ns
NRD Controlled (READ_MODE = 0)			
SMC_{10}	Data Setup before NCS High	11.5	ns
SMC_{11}	Data Hold after NCS High	0	ns
SMC_{12}	NCS High to NBS0/A0 Change[1]	ncs rd hold length * t_{CPSMC} - 2.3	ns
SMC_{13}	NCS High to NBS0/A0 Change[1]	ncs rd hold length * t_{CPSMC} - 2.3	ns
SMC_{14}	NCS High to NBS2/A1 Change[1]	ncs rd hold length * t_{CPSMC} - 2.3	ns
SMC_{16}	NCS High to A2 - A23 Change[1]	ncs rd hold length * t_{CPSMC} - 4	ns
SMC_{17}	NCS High to NRD Inactive[1]	ncs rd hold length - nrd hold length)* t_{CPSMC} - 1.3	ns
SMC_{18}	NCS Pulse Width	ncs rd pulse length * t_{CPSMC} - 3.6	ns

Note: 1. hold length = total cycle duration - setup duration - pulse duration. “hold length” is for “ncs rd hold length” or “nrd hold length”.

Figure 7-8. SMC Signals for NRD and NRW Controlled Accesses.



7.11.2 SDRAM Signals

These timings are given for 10 pF load on SDCK and 40 pF on other signals.

Table 7-35. SDRAM Clock Signal.

Symbol	Parameter	Conditions	Min.	Max.(1)	Unit
$1/(t_{CPSDCK})$	SDRAM Controller Clock Frequency			$1/(t_{cpcpu})$	MHz

Note: 1. The maximum frequency of the SDRAMC interface is the same as the max frequency for the HSB.

Table 7-36. SDRAM Clock Signal

Symbol	Parameter	Conditions	Min.	Max.	Unit
$SDRAMC_1$	SDCKE High before SDCK Rising Edge		7.4		ns
$SDRAMC_2$	SDCKE Low after SDCK Rising Edge		3.2		ns
$SDRAMC_3$	SDCKE Low before SDCK Rising Edge		7		ns
$SDRAMC_4$	SDCKE High after SDCK Rising Edge		2.9		ns
$SDRAMC_5$	SDCS Low before SDCK Rising Edge		7.5		ns
$SDRAMC_6$	SDCS High after SDCK Rising Edge		1.6		ns
$SDRAMC_7$	RAS Low before SDCK Rising Edge		7.2		ns
$SDRAMC_8$	RAS High after SDCK Rising Edge		2.3		ns
$SDRAMC_9$	SDA10 Change before SDCK Rising Edge		7.6		ns
$SDRAMC_{10}$	SDA10 Change after SDCK Rising Edge		1.9		ns
$SDRAMC_{11}$	Address Change before SDCK Rising Edge		6.2		ns
$SDRAMC_{12}$	Address Change after SDCK Rising Edge		2.2		ns

8.3 Soldering Profile

Table 8-5 gives the recommended soldering profile from J-STD-20.

Table 8-5. Soldering Profile

Profile Feature	**Green Package**
Average Ramp-up Rate (217°C to Peak)	3°C/Second max
Preheat Temperature 175°C ±25°C	150-200°C
Time Maintained Above 217°C	60-150 seconds
Time within 5°C of Actual Peak Temperature	30 seconds
Peak Temperature Range	260 (+0/-5°C)
Ramp-down Rate	6°C/Second max.
Time 25°C to Peak Temperature	8 minutes max

Note: It is recommended to apply a soldering temperature higher than 250°C.

A maximum of three reflow passes is allowed per component.

For higher polling time, the software must freeze the pipe for the desired period in order to prevent any "extra" token.

10.1.5 ADC

Sleep Mode activation needs additional A to D conversion
If the ADC sleep mode is activated when the ADC is idle the ADC will not enter sleep mode before after the next AD conversion.
Fix/Workaround
Activate the sleep mode in the mode register and then perform an AD conversion.

10.1.6 USART

ISO7816 info register US_NER cannot be read
The NER register always returns zero.
Fix/Workaround
None.

The LIN ID is not transmitted in mode PDCM='0'
Fix/Workaround
Using USART in mode LIN master with the PDCM bit = '0', the LINID written at the first address of the transmit buffer is not used. The LINID must be written in the LINIR register, after the configuration and start of the PDCA transfer. Writing the LINID in the LINIR register will start the transfer whenever the PDCA transfer is ready.

The LINID interrupt is only available for the header reception and not available for the header transmission
Fix/Workaround
None.

USART LIN mode is not functional with the PDCA if PDCM bit in LINMR register is set to 1
If a PDCA transfer is initiated in USART LIN mode with PDCM bit set to 1, the transfer never starts.
Fix/Workaround
Only use PDCM=0 configuration with the PDCA transfer.

10.1.7 SPI

SPI disable does not work in SLAVE mode
SPI disable does not work in SLAVE mode.
Fix/Workaround
Read the last received data, then perform a software reset by writing a one to the Software Reset bit in the Control Register (CR.SWRST).

SPI bad serial clock generation on 2nd chip_select when SCBR=1, CPOL=1, and NCPHA=0
When multiple chip selects (CS) are in use, if one of the baudrates equal 1 while one (CSRn.SCBR=1) of the others do not equal 1, and CSRn.CPOL=1 and CSRn.NCPHA=0, then an additional pulse will be generated on SCK.
Fix/Workaround
When multiple CS are in use, if one of the baudrates equals 1, the others must also equal 1 if CSRn.CPOL=1 and CSRn.NCPHA=0.

TWIS stretch on Address match error
When the TWIS stretches TWCK due to a slave address match, it also holds TWD low for the same duration if it is to be receiving data. When TWIS releases TWCK, it releases TWD at the same time. This can cause a TWI timing violation.
Fix/Workaround
None.

10.1.14 SSC

Frame Synchro and Frame Synchro Data are delayed by one clock cycle
The frame synchro and the frame synchro data are delayed from 1 SSC_CLOCK when:
- Clock is CKDIV
- The START is selected on either a frame synchro edge or a level
- Frame synchro data is enabled
- Transmit clock is gated on output (through CKO field)

Fix/Workaround
Transmit or receive CLOCK must not be gated (by the mean of CKO field) when START condition is performed on a generated frame synchro.

10.1.15 FLASHC

Corrupted read in flash may happen after fuses write or erase operations (FLASHC LP, UP, WGPB, EGPB, SSB, PGPFB, EAGPF commands)
After a flash fuse write or erase operation (FLASHC LP, UP, WGPB, EGPB, SSB, PGPFB, EAGPF commands), reading (data read or code fetch) in flash may fail. This may lead to an exception or to other errors derived from this corrupted read access.
Fix/Workaround
Before the flash fuse write or erase operation, enable the flash high speed mode (FLASHC HSEN command). The flash fuse write or erase operations (FLASHC LP, UP, WGPB, EGPB, SSB, PGPFB, EAGPF commands) must be issued from RAM or through the EBI. After these commands, read 3 times one flash page initialized to 00h. Disable the flash high speed mode (FLASHC HSDIS command). It is then possible to safely read or code fetch the flash.

10.2 Rev. E

10.2.1 General

Devices cannot operate with CPU frequency higher than 66MHz in 1WS and 36MHz in 0WS
Fix/Workaround
None

Increased Power Consumption in VDDIO in sleep modes
If the OSC0 is enabled in crystal mode when entering a sleep mode where the OSC0 is disabled, this will lead to an increased power consumption in VDDIO.
Fix/Workaround
Disable the OSC0 through the System Control Interface (SCIF) before going to any sleep mode where the OSC0 is disabled, or pull down or up XIN0 and XOUT0 with 1 Mohm resistor.

Power consumption in static mode The power consumption in static mode can be up to 330µA on some parts (typical at 25°C)

Fix/Workaround
Set to 1b bit CORRS4 of the ECCHRS mode register (MD). In C-code: *((volatile int*) (0xFFFE2404))= 0x400.

DMACA data transfer fails when CTLx.SRC_TR_WIDTH is not equal to CTLx.DST_TR_WIDTH
Fix/Workaround
For any DMACA transfer make sure CTLx.SRC_TR_WIDTH = CTLx.DST_TR_WIDTH.

3.3V supply monitor is not available
FGPFRLO[30:29] are reserved and should not be used by the application.
Fix/Workaround
None.

Service access bus (SAB) can not access DMACA registers
Fix/Workaround
None.

10.2.2 Processor and Architecture

LDM instruction with PC in the register list and without ++ increments Rp
For LDM with PC in the register list: the instruction behaves as if the ++ field is always set, ie the pointer is always updated. This happens even if the ++ field is cleared. Specifically, the increment of the pointer is done in parallel with the testing of R12.
Fix/Workaround
None.

Hardware breakpoints may corrupt MAC results
Hardware breakpoints on MAC instructions may corrupt the destination register of the MAC instruction.
Fix/Workaround
Place breakpoints on earlier or later instructions.

When the main clock is RCSYS, TIMER_CLOCK5 is equal to PBA clock
When the main clock is generated from RCSYS, TIMER_CLOCK5 is equal to PBA Clock and not PBA Clock / 128.
Fix/Workaround
None.

10.2.3 MPU

Privilege violation when using interrupts in application mode with protected system stack
If the system stack is protected by the MPU and an interrupt occurs in application mode, an MPU DTLB exception will occur.
Fix/Workaround
Make a DTLB Protection (Write) exception handler which permits the interrupt request to be handled in privileged mode.

10.2.4 USB

UPCFGn.INTFRQ is irrelevant for isochronous pipe
As a consequence, isochronous IN and OUT tokens are sent every 1ms (Full Speed), or every 125uS (High Speed).